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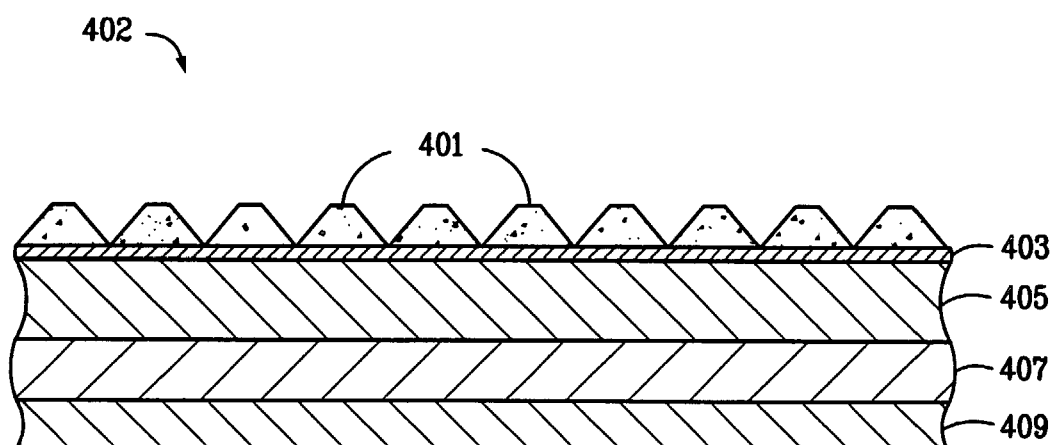
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(54) Title: FIXED ABRASIVE LINEAR POLISHING BELT AND SYSTEM USING THE SAME



(57) Abstract: A belt (402) for polishing a workpiece such as a semiconductor wafer in a linear chemical mechanical polishing system includes a fixed abrasive material (401) attached to a polymeric layer (405) forming an endless loop. The belt is made without any reinforcing or supporting layers or supporting components or, in the alternative, with a soft, highly porous sublayer (407), allowing the belt to bend readily around the rollers (104, 106) of the linear polishing belt. Between the fixed abrasive material (401) and the polymeric support layer, an attachment material (403) is present. The bottom side of the polymeric sublayer can be attached to a stainless steel layer (409).



WO 01/074535 A1